

NPN 100mA 50V Digital Transistor (Bias Resistor Built-in Transistor)

Parameter	Value
V _{CEO}	50V
Ι _C	100mA
R ₁	10kΩ

Features

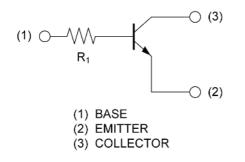
- 1) Built-In Biasing Resistor
- Built-in bias resistors enable the configuration of an inverter circuit without connecting external input resistors (see inner circuit).
- 3) Only the on/off conditions need to be set for operation, making the circuit design easy.
- 4) Complementary PNP Types: DTA114T series

Application

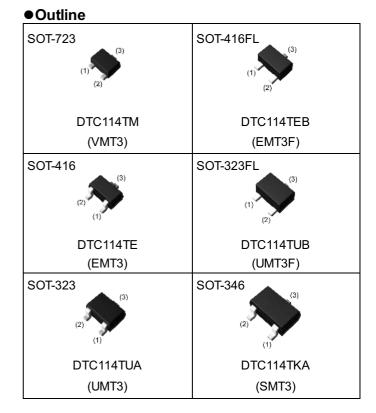
INVERTER, INTERFACE, DRIVER

Inner circuit

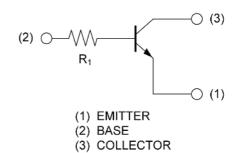
DTC114TM/ DTC114TEB/ DTC114TUB



Packaging specifications



DTC114TE/ DTC114TUA/ DTC114TKA



• I ackaging sp	ecilications						
Part No.	Package	Package size	Taping code	Reel size (mm)	Tape width (mm)	Basic ordering unit.(pcs)	Marking
DTC114TM	SOT-723	1212	T2L	180	8	8000	04
DTC114TEB	SOT-416FL	1616	TL	180	8	3000	04
DTC114TE	SOT-416	1616	TL	180	8	3000	04
DTC114TUB	SOT-323FL	2021	TL	180	8	3000	04
DTC114TUA	SOT-323	2021	T106	180	8	3000	04
DTC114TKA	SOT-346	2928	T146	180	8	3000	04

DTC114T series

• Absolute maximum ratings ($T_a = 25^{\circ}C$)

Pa	arameter	Symbol	Values	Unit
Collector-base voltage		V _{CBO}	50	V
Collector-emitter voltage			50	V
Emitter-base voltage			5	V
Collector current			100	mA
	DTC114TM		150	
	DTC114TEB		150	
Dower disaination	DTC114TE		150	ma)///
Power dissipation	DTC114TUB	ΓD.	200	— mW
	DTC114TUA		200	
	DTC114TKA		200	
Junction temperature		Tj	150	°C
Range of storage temperat	ure	T _{stg}	-55 to +150	°C

•Electrical characteristics (T_a = 25°C)

Dementer	O: make a l			Values		1.114	
Parameter	Symbol Conditions		Min.	Тур.	Max.	Unit	
Collector-base breakdown voltage	BV _{CBO}	Ι _C = 50μΑ	50	-	-	V	
Collector-emitter breakdown voltage	BV _{CEO} I _C = 1mA		50	-	-	V	
Emitter-base breakdown voltage	BV_{EBO}	Ι _Ε = 50μΑ	5	-	-	V	
Collector cut-off current	I _{CBO}	V _{CB} = 50V	-	-	500	nA	
Emitter cut-off current	I _{EBO}	V _{EB} = 4V	-	-	500	nA	
Collector-emitter saturation voltage	V _{CE(sat)}	I _C = 10mA, I _B = 1mA	-	-	300	mV	
DC current gain	h _{FE}	V _{CE} = 5V, I _C = 1mA	100	250	600	-	
Input resistance	R ₁	-	7	10	13	kΩ	
Transition frequency	f _T *2	V _{CE} = 10V, I _E = -5mA, f = 100MHz	-	250	-	MHz	

*1 Each terminal mounted on a reference land.

*2 Characteristics of built-in transistor



10

1

0.1

0.01

0.001

0

0.5

V_{CE}=5

Pulsed

450µA

400µA

350µA

300µA

250µA

200µA

150µA

100µA

10

Ta=25°C

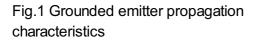
Pulsed

8

50µA

6

● Electrical characteristic curves(Ta=25°C)



Ta=125°C

1.0

BASE TO EMITTER VOLTAGE : V_{BE} [V]

75°C

25°C -40°C

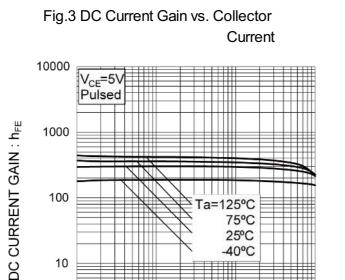
1.5

-40°C

10

2.0

COLLECTOR CURRENT : I_c [mA]



1

COLLECTOR CURRENT : Ic [mA]

Fig.4 Collector-Emitter Saturation Voltage vs. Collector Current

4

COLLECTOR TO EMITTER VOLTAGE : V_{CE} [V]

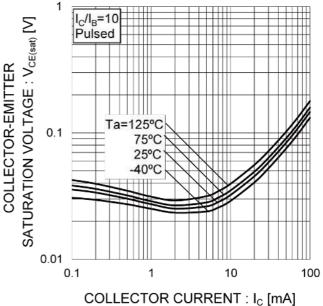


Fig.2 Typical Output Characteristics

100

80

60

40

20

0

0

2

COLLECTOR CURRENT : I_c [mA]

I_B= 500μA

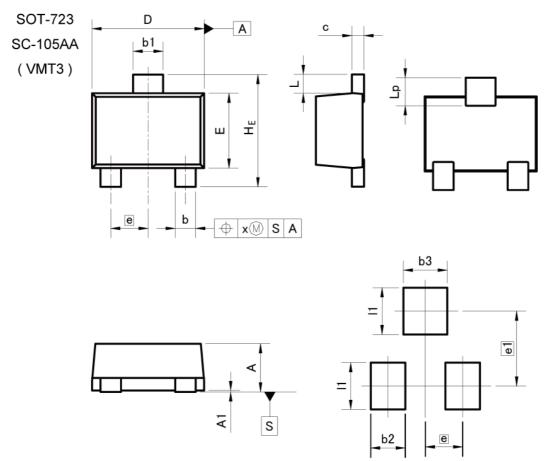
10

1

0.1



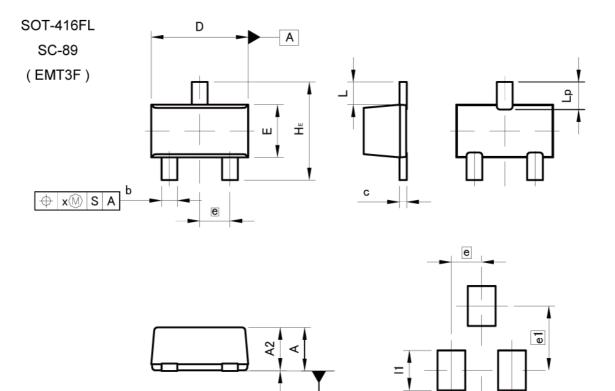
100



Pattern of terminal position areas [Not a pattern of soldering pads]

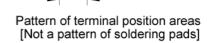
DIM	MILIM	ETERS	INC	HES
	MIN	MAX	MIN	MAX
A	0.45	0.55	0.018	0.022
A1	0.00	0.10	0.000	0.004
b	0.17	0.27	0.007	0.011
b1	0.27	0.37	0.011	0.015
с	0.08	0.18	0.003	0.007
D	1.10	1.30	0.043	0.051
E	0.70	0.90	0.028	0.035
e	0.40		0.02	
HE	1.10	1.30	0.043	0.051
L	0.10	0.30	0.004	0.012
Lp	0.20	0.40	0.008	0.016
х		0.10		0.004
	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
b2	2 40	0.37		0.015
b3	222)	0.47	1.00	0.019
e1	0.	80	0.0	31
11	55.H	0.50	100	0.020





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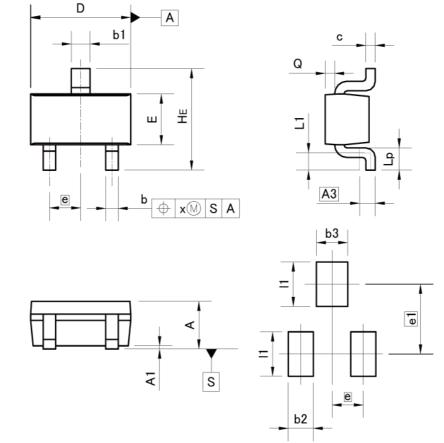
b2

DIM	MILIM	ETERS	INC	HES	
	MIN	MAX	MIN	MAX	
A	0.65	0.85	0.026	0.033	
A1	0.00	0.10	0.000	0.004	
A2	0.60	0.80	0.024	0.031	
b	0.21	0.36	0.008	0.014	
с	0.08	0.18	0.003	0.007	
D	1.50	1.70	0.059	0.067	
E	0.76	0.96	0.030	0.038	
е	0.50		0.020		
He	1.50	1.70	0.059	0.067	
L	0.	37	0.015		
Lp	0.35	0.55	0.014	0.022	
x	1778	0.10		0.004	
	MILIMETERS		INC	HES	
	MIN	MAX	MIN	MAX	
b2	1	0.46	-	0.018	
e1		1.05	-	0.041	
11	44	0.65		0.026	





(EMT3)

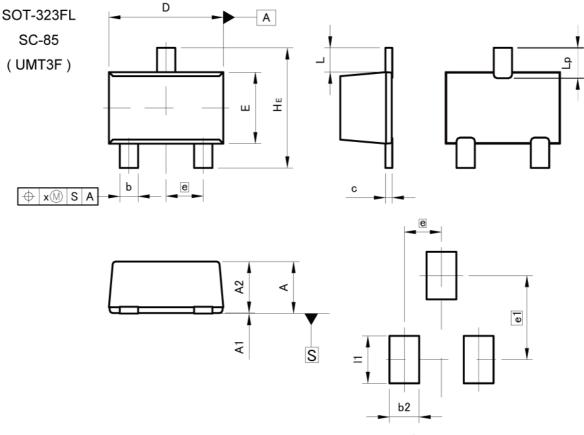


Pattern of terminal position areas [Not a pattern of soldering pads]

	MILIM	ETERS	INC	HES
	MIN	MAX	MIN	MAX
A	0.60	0.80	0.024	0.031
A1	0.00	0.10	0.000	0.004
A3	0.	25	0.0	10
b	0.15	0.30	0.006	0.012
b1	0.25	0.40	0.010	0.016
с	0.10	0.20	0.004	0.008
D	1.50	1.70	0.059	0.067
E	0.70	0.90	0.028	0.035
е	0.	50	0.020	
HE	1.40	1.80	0.055	0.071
L1	0.10		0.004	8
Lp	0.15	. 	0.006	2.00
Q	0.05	0.25	0.002	0.010
x	1915	0.10		0.004

DIM -	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b2	20 14	0.40	(H)	0.016
b3		0.50	. 	0.020
e1	1.	10	0.0	043
11	8.000	0.70	-	0.028





Pattern of terminal position areas [Not a pattern of soldering pads]

	MILIM	ETERS	INC	HES
	MIN	MAX	MIN	MAX
A	0.85	1.05	0.033	0.041
A1	0.00	0.10	0.000	0.004
A2	0.80	1.00	0.031	0.039
b	0.27	0.42	0.011	0.017
с	0.08	0.18	0.003	0.007
D	1.90	2.10	0.075	0.083
E	1.15	1.35	0.045	0.053
e	0.65		0.026	
HE	2.00	2.20	0.079	0.087
L	0.4	25	0.017	
Lp	0.43	0.63	0.017	0.025
x	. 	0.10	1000	0.004
DIM	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
b2	-	0.52	-	0.020
e1	1.47		0.0	58

Dimension in mm/inches

-

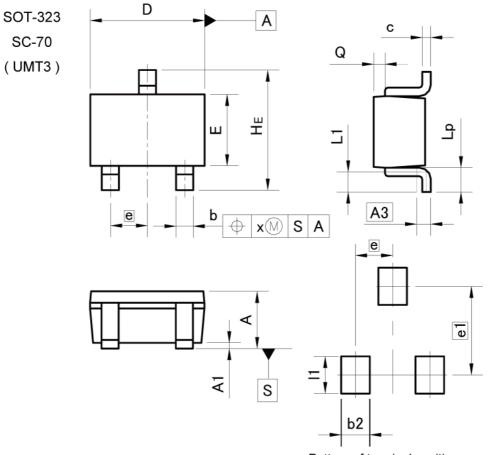
11



0.033

0.83

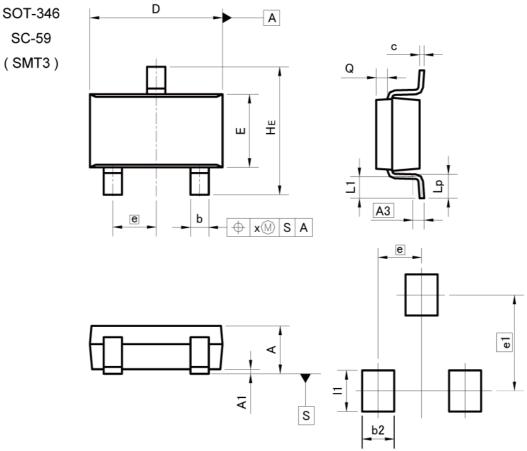
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Pattern of terminal position areas [Not a pattern of soldering pads]

	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
A	0.80	1.00	0.031	0.039
A1	0.00	0.10	0.000	0.004
A3	0.1	25	0.0	10
b	0.25	0.40	0.010	0.016
С	0.10	0.20	0.004	0.008
D	1.90	2.10	0.075	0.083
E	1.15	1.35	0.045	0.053
e	0.65		0.026	
HE	2.00	2.20	0.079	0.087
L1	0.10	0.40	0.004	0.016
Lp	0.25	0.55	0.010	0.022
Q	0.10	0.30	0.004	0.012
х	 :	0.10	-	0.004
	MILIMETERS		INC	HES
	MIN	MAX	MIN	MAX
b2		0.50	1 <u>111</u>	0.020
e1	1.	55	0.0	61
11		0.65	2 (177)	0.026





Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	1.00	1.30	0.039	0.051
A1	0.00	0.10	0.000	0.004
A3	0.	25	0.0	10
b	0.35	0.50	0.014	0.020
С	0.09	0.25	0.004	0.010
D	2.80	3.00	0.110	0.118
E	1.50	1.80	0.059	0.071
е	0.95		0.037	
HE	2.60	3.00	0.102	0.118
L1	0.30	0.60	0.012	0.024
Lp	0.40	0.70	0.016	0.028
Q	0.20	0.30	0.008	0.012
x		0.10	4 7.	0.004
У	=	0.10	8 75	0.004
			500	
DIM	MILIMETERS		INC	HES
UTIVI	MIN	MAX	MIN	MAX
b2	-7	0.60	21	0.024
e1	2.	10	0.0	83

Dimension in mm/inches

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11



0.035

0.90

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Notice

Precaution on using ROHM Products

1. Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment ^(Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CLASSI
CLASSⅣ		CLASSⅢ	

- 2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
 - [a] Installation of protection circuits or other protective devices to improve system safety
 - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
- 3. Our Products are designed and manufactured for use under standard conditions and not under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
 - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

Precaution for Product Label

A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

Precaution for Foreign Exchange and Foreign Trade act

Since concerned goods might be fallen under listed items of export control prescribed by Foreign exchange and Foreign trade act, please consult with ROHM in case of export.

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